



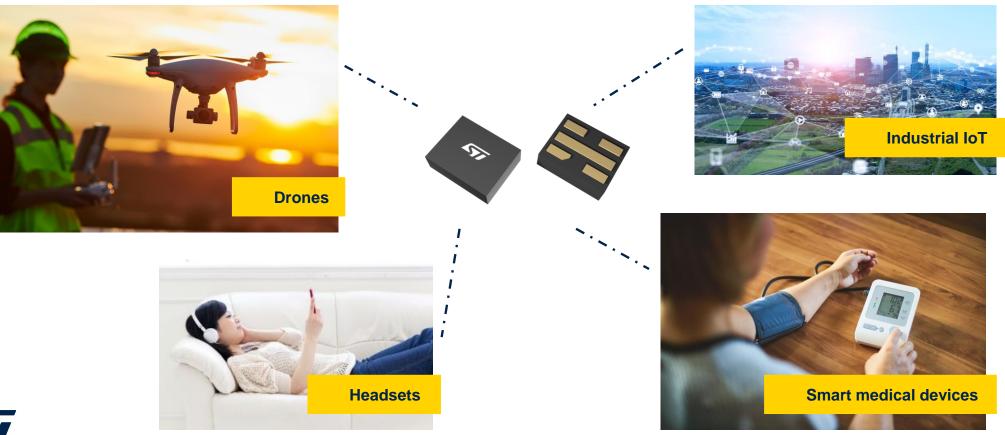
## Serial I2C EEPROM in DFN5 package





#### Target applications DFN5 package

Designed for applications where **space and weight constraints** and **manufacturing robustness** are key factors



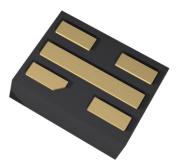


## DFN5 package features

**DFN5 package offers significant improvement vs. DFN8** 

#### DFN5

Other market package names UFDFPN5\* or MLP5



\* UFDFPN: Ultra-thin Fine-pitch Dual Flat Package No lead

Features	DFN5		DFN8	
Package size	1.4 x 1.7 mm		2 x 3 mm	
Thickness	0.55 mm		0.55 mm	
Weight	7 mg		16 mg	
Pin count	5 pin		8 pin	
Pin type	Leadless package		Leadless	
Solder pitch	0.4 mm		0.5 mm	

Package information and soldering guidelines available in TN1171





## DFN5 package benefits

Features	Benefits		
Wide I <sup>2</sup> C portfolio Available in 2, 4, 8, 16, 32, 64, 128 and 256 Kbits	Easy upgrade thanks to same footprint for all densities		
Package size: 1.4 x 1.7 mm	Minimize PCB footprint and gain at least 60% space versus DFN8		
5 pin count and no leads	Reduce soldering budget and wire routing on PCB		
Weight: 7mg	Gain on application weight		
Robust molded package & 0.4mm pitch	Small package with easy handling and mounting		
ECOPACK2®	RoHS-compliant and halogen-free		





# I2C EEPROM DFN5 Portfolio

#### **I2C EEPROM** in DFN5 package offers:

- reduced PCB footprint
- reduced application weight
- easy handling and manufacturing robustness

Profile description	Part number	Memory density (Kbits)	Dimensio (mn		Profile (typ.) (mm)	Nb of pins	Weight (mg)
<b>DFN5</b> (UFDFPN5 – MLP5)	<u>M24C02-F<b>MH</b>6TG</u>	2	1.7	1.4	0.55	5	7
	<u>M24C04-F<b>MH</b>6TG</u>	4	1.7	1.4	0.55	5	7
	<u>M24C08-F<b>MH</b>6TG</u>	8	1.7	1.4	0.55	5	7
	<u>M24C16-F<b>MH</b>6TG</u>	16	1.7	1.4	0.55	5	7
	<u>M24C32-F<b>MH</b>6TG</u>	32	1.7	1.4	0.55	5	7
	<u>M24C64-F<b>MH</b>6TG</u>	64	1.7	1.4	0.55	5	7
	<u>M24128-BF<b>MH</b>6TG</u>	128	1.7	1.4	0.55	5	7
	<u>M24256E-F<b>MH</b>6TG</u>	256	1.7	1.4	0.55	5	7



# Serial EEPROM - make it easy



#### ST EEPROM Finder app

Select & order the right EEPROM for your design



#### X-Nucleo-EEPRMA2 Plug-in shield

Prototype and validate







### I2C EEPROM in DFN5 package summary

#### Designed for small & light modules where robustness is a key factor

- Wide I2C portfolio up to 256 Kbits
- Robust ROHS and lead-free package
- Samples available now

- Download EEPROM finder mobile APP
- Apply for free ST samples or buy from e-store
- Prototype with X-Nucleo-EEPRMA2 shield
- IBIS & soldering guidelines available on st.com



# Thank you

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